

**REMARKS**

Applicants respectfully request the Examiner to enter the above amendments prior to the examination of this application.

**Status of Claims**

Claims 7 to 18 will be pending after entry of the present amendment. Claim 1 is being canceled without prejudice.

**Amendment**

The specification is being amended to insert section headers and an abstract of the disclosure in accordance with 37 CFR §1.77 to better conform with US patent practice. The specification is also being amended to insert a cross-reference to related applications in accordance with 37 CFR §1.78 and to claim priority to those applications listed therein.

New Claims 7 to 18 replace original Claims 1 to 6, and are being presented to better conform with US patent practice. These new claims are supported by the specification for example as shown in the Table below (cites to the specification are for the English translation):

Claim	Support in Specification
7	page 6, lines 1 to 15, page 9, lines 10 to 30, page 10, lines 6 to 10, original claim 2, page 12, lines 13 to 18
8, 9, 10	page 6, lines 9 to 22
11	page 9, lines 10 to 24
12	page 9, line 25 to page 10, line 5
13, 16	page 8, lines 20 to 29
14, 15, 17, 18	page 12, lines 13 to 18

No new matter is added by the new claims or amendments to the specification.

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CONCLUSION

The Assistant Commissioner is authorized to charge any deficiency in the required fee or to credit any overpayment to Deposit Account 01-1250 in connection with this amendment.

Respectfully submitted,

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### Abstract of the Disclosure

The present invention relates to process for producing a card body, such as a smart card or transponder. The process uses a thermoplastic hot-melt adhesive having a processing viscosity ranging from 100 mPa·s to 100,000 mPa·s to form a card body component layer containing an electronic circuit (e.g., chip) or transponder.

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